



Thanks to members!

This is the second English journal on electronics packaging and its related issues. Last year, the Japan Institute of Electronics Packaging (JIEP) decided to publish the English journal in order to provide information on Jisso technology including assembling, packaging, mounting and interconnection, and to share new ideas for developing future devices with engineers and scientists worldwide. The JIEP welcomes all the contributions to the journal from engineers and scientists. Last year, the first journal published 10 papers and the second journal has published 25 papers. Professor Hajime Tomokage, the first editor-in-chief of this journal said “We believe that the level of semiconductor assembling and packaging technology in Japan has been high so far, but we Japanese are not good at making English presentations to overseas engineers. We have noticed that it is important for Japanese to send technical information on Jisso to the world over. The JIEP certainly welcomes the submission of exciting papers from overseas countries. We hope that we can stimulate each other by sharing the state-of-the-art ideas and technology through this journal.” The increase of submitted papers proves the realization of Prof. Tomokage’s hope. Moreover, this journal has accepted 5 papers which were submitted from overseas. I hope the third journal will publish even more such papers. I would like to thank all the editors who worked hard on this second publication. Finally, I would also like to thank the JIEP members for submitting papers, especially the committee of the International Conference on Electronics Packaging 2009 (ICEP 2009), and I look forward to the support of ICEP 2010.

December 1, 2009

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■Preface – Thanks to members! / Ichiro KOIWA

■Original Articles

Reduction of the Oxide Layer on a Lead-Free Solder Material by Hydrogen Radicals / S. KAGATA, T. NAKASHIMA and A. IZUMI	1
Multi-Chip Module Fabricated by W-CSP Method using Excimer Laser Via-Hole Formation and Cu Plating / Takashi SUZUKI, Toshio TAMURA, Atsushi FUJISAKI, Kentaro KOIWA, Tadaaki YAMADA, Yohei WAKUDA, Satoshi ANDO, Akira MATSUNO and Ichiro KOIWA	5
Basic Research on the Metallization of Aluminum Pads, Silicon Nitride and Polyimide by Electroless Nickel-Phosphorus Plating / Yuki HAIJIMA, Kazuki TAKAGI, Tatsuma KANEDA and Ichiro KOIWA	13
Shape Control of Electronic Devices by Soldering / Hiroshi KIKUCHI, Norio NAKAZATO, Naotaka TANAKA and Toshihiko SATO	19
Effect of Impurities of Au and Pd on Tensile Properties of Eutectic Sn–Pb Solder for Aerospace Applications / Ikuo SHOHJI, Yuta SAITOH, Norio NEMOTO, Tsuyoshi NAKAGAWA, Nobuaki EBIHARA and Fusao IWASE	29
Comparison of Erosion Rates of SUS304 and SUS316 Stainless Steels by Molten Sn–3Ag–0.5Cu Solder / Ikuo SHOHJI, Kazuhito SUMIYOSHI and Makoto MIYAZAKI	35
Advanced Fine-Line Thick-Film Conductors with High Conductivity and Soldering Capability Built by Screen-Printing / Takashi YAMAMOTO and Dominique NUMAKURA	40
Inhibiting Cracking of Interfacial Cu ₆ Sn ₅ by Ni Additions to Sn-based Lead-free Solders / Kazuhiro NOGITA, Stuart D. McDONALD, Hideaki TSUKAMOTO, Jonathan READ, Shoichi SUENAGA and Tetsuro NISHIMURA	46
Effect of Additives in the Electrolyte on the Physical Properties of Electrodeposited Copper / Mitsuyoshi MATSUDA, Takuya TAKAHASHI, Sachio YOSHIHARA and Makoto DOBASHI	55
Mechanical Shock Durability Studies of Sn–Ag–Cu–Ni BGA Solder Joints on Electroless Ni–P/Au Surface Finish / Fumiyoshi KAWASHIRO, Hajime YANASE, Masato UJIIE, Takaki ETOU and Hiroshi OKADA	62
Analysis of Complete Power-Distribution Network and Co-Design Optimization / Narimasa TAKAHASHI, Masahide NOSE, Satoshi KAEKO and Yo TAKAHASHI	69
Printed Electronics on Flexible Substrate Using Inkjet Technology / Shinichi NISHI, Kazuo ASANO, Daisuke ISHIBASHI, Akiko KITAMI and Kumiko FURUNO	75
Pb-Free High Temperature Solder Joints for Power Semiconductor Devices / Yasushi YAMADA, Yoshikazu TAKAKU, Yuji YAGI, Ikuo NAKAGAWA, Takashi ATSUMI, Mikio SHIRAI, Ikuo OHNUMA and Kiyohito ISHIDA	79
Wettability and Reliability for Double-Sided Assembly with Chip Connection (C2) Flip-Chip Technology / Hirokazu NOMA, Yukifumi OYAMA, Hidetoshi NISHIWAKI, Masahide TAKAMI, Toshiyuki TAKATANI, Kazushige TORIYAMA and Yasumitsu ORII	85
Effect of the Formation of the Intermetallic Compounds between a Tin Bump and an Electroplated Copper Thin Film on both the Mechanical and Electrical Properties of the Jointed Structures / Seongcheol JEONG, Naokazu MURATA, Yuki SATO, Ken SUZUKI and Hideo MIURA	91
Effects of a Third Element on Microstructure and Mechanical Properties of Eutectic Sn–Bi Solder / Seiki SAKUYAMA, Toshiya AKAMATSU, Keisuke UENISHI and Takehiko SATO	98
A Multilayer Process for 3D-Molded-Interconnect-Devices to Enable the Assembly of Area-Array Based Package Types / T. LENEKE and S. HIRSCH	104
Formation of Au Microbump Arrays for Flip-Chip Bonding Using Electroless Au Deposition from a Non-Cyanide Plating Bath / Tokihiko YOKOSHIMA, Kentaro NOMURA, Yasuhiro YAMAJI, Katsuya KIKUCHI, Hiroshi NAKAGAWA, Kohji KOSHII, Masahiro AOYAGI, Ryota IWAI, Tomoaki TOKUHISA and Masaru KATO	109
Fabrication of RF Circuit Structures on a PCB Material Using Inkjet Printing-Electroless Plating and the Substrate Preparation for the Same / A. SRIDHAR, M. A. PERIK, J. REIDING, D. J. van DIJK and R. AKKERMAN	116
Effects of Multi-modal Filler Size Distributions on Thermal Conductivity of Electrically Conductive Adhesives Containing Ag Micro and Nanoparticles / M. INOUE and J. LIU	125
IMB Technology for Embedded Active and Passive Components in SiP, SiB and Single IC Package Applications / R. TUOMINEN, T. WARIS and J. METTOVAARA	134
The Electrical Characteristics Investigation of the Module-Level Miniaturization with Embedded Device Technology / Shuji SAGARA and Masaya TANAKA	139
Bandpass Filter Embedded SwP (System with Probe) for High-Frequency Application / Keiji MATSUMOTO, Ryota SAITO, Woon CHOI and Hajime TOMOKAGE	148
Thermal Characterization of a Three-Dimensional (3D) Chip Stack / Keiji MATSUMOTO and Yoichi TAIRA	153
Inter Chip Fill for 3D Chip Stack / A. HORIBE, F. YAMADA, C. FEGER and J. U. KNICKERBOCKER	160